

CMOS STATIC RAM 1 MEG (256K x 4-BIT)

IDT71028

FEATURES:

- 256K x 4 advanced high-speed CMOS static RAM
- Equal access and cycle times
 - Commercial: 12/15/17/20ns
- One Chip Select plus one Output Enable pin
- Bidirectional data Inputs and outputs directly TTL-compatible
- · Low power consumption via chip deselect
- · Available in 400 mil Plastic SOJ package

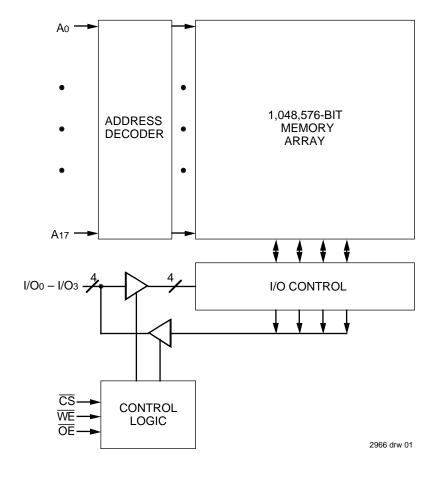
DESCRIPTION:

The IDT71028 is a 1,048,576-bit high-speed static RAM organized as 256K x 4. It is fabricated using IDT's high-perfomance, high-reliability CMOS technology. This state-of-the-art technology, combined with innovative circuit design techniques, provides a cost-effective solution for high-speed memory needs.

The IDT71028 has an output enable pin which operates as fast as 6ns, with address access times as fast as 12ns. All bidirectional inputs and outputs of the IDT71028 are TTL-compatible and operation is from a single 5V supply. Fully static asynchronous circuitry is used, requiring no clocks or refresh for operation.

The IDT71028 is packaged in 28-pin 400 mil Plastic SOJ package.

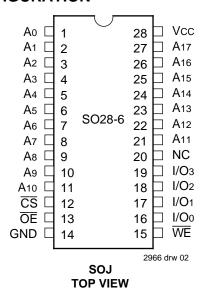
FUNCTIONAL BLOCK DIAGRAM



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PIN CONFIGURATION



TRUTH TABLE(1,2)

<u>cs</u>	ŌĒ	WE	I/O	Function
L	L	Н	DATAout	Read Data
L	Χ	L	DATAIN	Write Data
L	Н	Н	High-Z	Output Disabled
Н	Χ	Χ	High-Z	Deselected - Standby (IsB)
VHC ⁽³⁾	Х	Х	High-Z	Deselected - Standby (ISB1)

NOTES:

- 1. $H = V_{IH}$, $L = V_{IL}$, x = Don't care.
- 2. VLC = 0.2V, VHC = VCC -0.2V.
- 3. Other inputs \geq VHC or \leq VLC.

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Com'l.	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7.0	V
ТА	Operating Temperature	0 to +70	°C
TBIAS	Temperature Under Bias	-55 to +125	°C
Tstg	Storage Temperature	–55 to +125	°C
Рт	Power Dissipation	1.25	W
Іоит	DC Output Current	50	mA

NOTES:

2966 tbl 02

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. VTERM must not exceed Vcc + 0.5V.

CAPACITANCE

 $(TA = +25^{\circ}C, f = 1.0MHz, SOJ package)$

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	8	pF
CI/O	I/O Capacitance	Vout = 3dV	8	pF

NOTE:

2966 tbl 01

2966 tbl 03

RECOMMENDED DC OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	٧
GND	Supply Voltage	0	0	0	V
VIH	Input High Voltage	2.2	_	Vcc+0.5	V
VIL	Input Low Voltage	$-0.5^{(1)}$	_	0.8	V

NOTE:

2966 tbl 04

DC ELECTRICAL CHARACTERISTICS

 $VCC = 5.0V \pm 10\%$

			IDT7		
Symbol	Parameter	Min.	Max.	Unit	
LI	Input Leakage Current	Vcc = Max., Vin = GND to Vcc	_	5	μА
ILO	Output Leakage Current	$VCC = Max., \overline{CS} = VIH, VOUT = GND to VCC$	_	5	μΑ
Vol	Output Low Voltage	IOL = 8mA, Vcc = Min.	_	0.4	V
Voн	Output High Voltage	IOH = -4mA, VCC = Min.	2.4	_	V

2966 tbl 05

This parameter is guaranteed by device characterization, but not production tested.

^{1.} VIL (min.) = -1.5V for pulse width less than 10ns, once per cycle.

DC ELECTRICAL CHARACTERISTICS⁽¹⁾

 $(VCC = 5.0V \pm 10\%, VLC = 0.2V, VHC = VCC - 0.2V)$

		71028S12 ⁽³⁾		71028S15		71028	S17	71028S20		
Symbol	Parameter	Com'l.	Mil.	Com'l.	Mil.	Com'l.	Mil.	Com'l.	Mil.	Unit
Icc	Dynamic Operating Current, CS ≤ VIL, Outputs Open, VCC = Max., f = fMAX ⁽²⁾	155		150		145	1	145		mA
ISB	Standby Power Supply Current (TTL Level), $\overline{\text{CS}} \ge \text{V}_{\text{IH}}$, Outputs Open, $\text{VCC} = \text{Max.}$, $\text{f} = \text{fmAx}^{(2)}$	35	_	35		35		35	_	mA
ISB1	Full Standby Power Supply Current (CMOS Level), $\overline{CS} \ge VHC$, Outputs Open, $VCC = Max.$, $f = 0^{(2)}$, $VIN \le VLC$ or $VIN \ge VHC$	10	_	10	_	10		10	_	mA

NOTES:

2966 tbl 06

- 1. All values are maximum guaranteed values.
- 2. fmax = 1/trc (all address inputs are cycling at fmax); f = 0 means no address input lines are changing.
- 3. 12ns specification is preliminary.

AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
AC Test Load	See Figures 1 and 2

2966 tbl 07

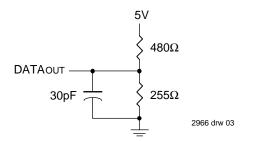
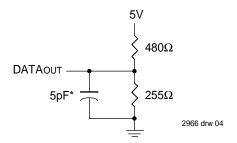


Figure 1. AC Test Load



*Including jig and scope capacitance.

Figure 2. AC Test Load (for tclz, tolz, tchz, tohz, tow, and twhz)

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AC ELECTRICAL CHARACTERISTICS (Vcc = $5.0V \pm 10\%$, Commercial Temperature Range)

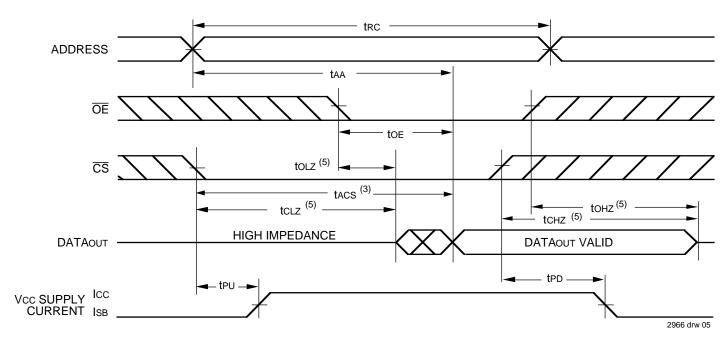
		7102	8S12 ⁽¹⁾	7102	28S15	71028S17		71028S20		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
Read Cy	cle									
trc	Read Cycle Time	12	_	15	_	17	_	20		ns
taa	Address Access Time	_	12	_	15	_	17	_	20	ns
tacs	Chip Select Access Time		12		15	_	17		20	ns
tcLz ⁽²⁾	Chip Select to Output in Low-Z	3	_	3	_	3		3	_	ns
tcHZ ⁽²⁾	Chip Deselect to Output in High-Z	0	6	0	7	0	8	0	8	ns
toe	Output Enable to Output Valid	_	6	_	7	_	8	_	8	ns
tolz ⁽²⁾	Output Enable to Output in Low-Z	0	_	0	_	0	_	0	_	ns
tonz ⁽²⁾	Output Disable to Output in High-Z	0	5	0	5	0	6	0	7	ns
tон	Output Hold from Address Change	4	_	4	_	4	_	4	_	ns
tpu ⁽²⁾	Chip Select to Power Up Time	0	_	0	_	0	_	0	_	ns
tPD ⁽²⁾	Chip Deselect to Power Down Time	_	12	_	15	_	17	_	20	ns
Write Cy	cle		•	•	•	•		•	•	
twc	Write Cycle Time	12	_	15	_	17	_	20	_	ns
taw	Address Valid to End of Write	10	_	12	_	13	_	15	_	ns
tcw	Chip Select to End of Write	10	_	12	_	13	-	15	_	ns
tas	Address Set-up Time	0	_	0	_	0	_	0	_	ns
twp	Write Pulse Width	10	_	12	_	13	-	15	_	ns
twr	Write Recovery Time	0	_	0	_	0	_	0	_	ns
tow	Data Valid to End of Write	7	_	8	_	9	_	9	_	ns
tDH	Data Hold Time	0	_	0	_	0		0	_	ns
tow ⁽²⁾	Output Active from End of Write	3	_	3	_	3	_	4	_	ns
twhz ⁽²⁾	Write Enable to Output in High-Z	0	5	0	5	0	7	0	8	ns

NOTES:

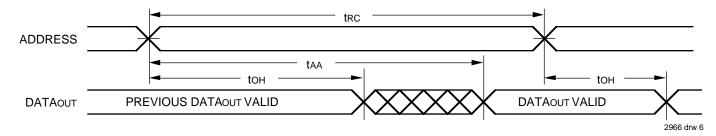
2966 tbl 08

 ^{1. 12}ns specification is preliminary.
 2. This parameter guaranteed with the AC load (Figure 2) by device characterization, but is not production tested.

TIMING WAVEFORM OF READ CYCLE NO. 1⁽¹⁾



TIMING WAVEFORM OF READ CYCLE NO. $2^{(1,2,4)}$

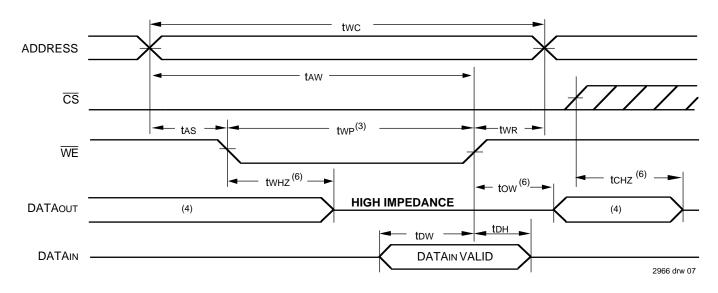


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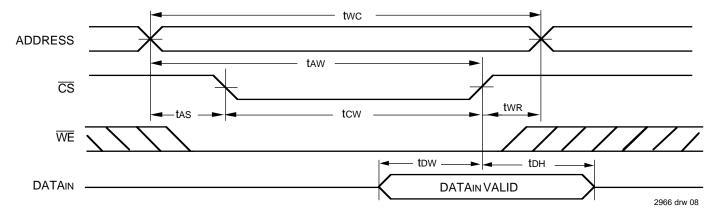
NOTES:

- 1. WE is HIGH for Read Cycle.
- 2. Device is continuously selected, \overline{CS} is LOW.
- 3. Address must be valid prior to or coincident with the later of $\overline{\text{CS}}$ transition LOW; otherwise tax is the limiting parameter.
- 4. $\overline{\text{OE}}$ is LOW.
- 5. Transition is measured $\pm 200 \text{mV}$ from steady state.

TIMING WAVEFORM OF WRITE CYCLE NO.1 ($\overline{\text{WE}}$ CONTROLLED TIMING) $^{(1,2,3,5)}$



TIMING WAVEFORM OF WRITE CYCLE NO.2 (CS CONTROLLED TIMING)(1,2,5)

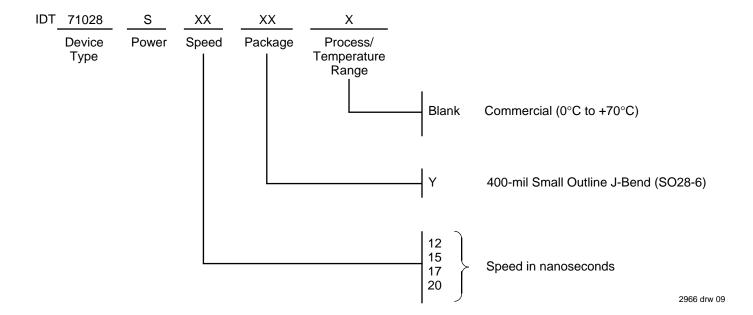


NOTES:

- 1. $\overline{\text{WE}}$ or $\overline{\text{CS}}$ must be HIGH during all address transitions.
- 2. A write occurs during the overlap of a LOW $\overline{\text{CS}}$ and a LOW $\overline{\text{WE}}$.
- 3. \overline{OE} is continuously \overline{HIGH} . If during a \overline{WE} controlled write cycle \overline{OE} is LOW, twp must be greater than or equal to twHz + tbw to allow the I/O drivers to turn off and data to be placed on the bus for the required tbw. If \overline{OE} is HIGH during a \overline{WE} controlled write cycle, this requirement does not apply and the minimum write pulse is as short as the specified twp.
- 4. During this period, I/O pins are in the output state, and input signals must not be applied.
- 5. If the CS LOW transition occurs simultaneously with or after the WE LOW transition, the outputs remain in a high-impedance state.
- 6. Transition is measured ±200mV from steady state.

9.4

ORDERING INFORMATION



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